

1. MATERIALS:

- HOUSING: PBT, BLACK, UL 94V-0
- SHIELD: 0.20mm THICK, BRASS PREPLATED WITH 0.76 μ m MIN SEMI-BRIGHT NICKEL; POST-DIPPED WITH 2.54 μ m MIN LEAD FREE SOLDER
- CONTACT TAILS: 0.25mm THICK, PHOSPHOR BRONZE, 1.27 μ m MIN OVERALL NICKEL UNDERPLATE, 2.54 μ m MIN TIN PLATE
- MOD JACK CONTACTS: 0.25mm THICK, PHOSPHOR BRONZE, 1.27 μ m MIN OVERALL NICKEL UNDERPLATE WITH 1.27 μ m MIN LOCALIZED GOLD PLATE AT PLUG INTERFACE

3 MAGNETICS

- APPLICATION: 10/100/1000 BASE-T, EXTENDED TEMPERATURE, PoE
- IMPEDANCE: 100 OHMS
- TURNS RATIO (CHIP: CABLE): 1:1 ALL FOUR PAIRS
- OPEN CIRCUIT INDUCTANCE (OCL): 350uH MIN @100kHz, 0.1VRMS,
8mADC BIAS FROM -40°C TO +85°C, ALL FOUR PAIRS
- ALL FOUR PAIRS BI-DIRECTIONAL
- POE CURRENT: 350mADC MAX
- PERFORMANCE @ 25°C:
 - INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHz TO 100MHz
 - RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 40MHz
12-20LOG(f/80)dB MIN FROM 40.1MHz TO 100MHz
 - CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
33-20LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
 - COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
- ISOLATION VOLTAGE: COMPLIES WITH IEEE802.3af 2003, PARA 33.4.1, ITEM a.

5. OPERATING TEMPERATURE: FROM -40°C TO $+85^{\circ}\text{C}$.

6. ALL DIMENSIONS NOMINAL UNLESS OTHERWISE NOTED.

7. TRP CONNECTOR LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.

8. PART SHOULD BE RECOMMENDED FOR WAVE SOLDERING PROCESS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C, 10 SECONDS MAX.

RI - R4 = 75 OHMS, 1/16W, 5% RESISTORS
 C1 - C4 = 22nF, 250V CAPACITORS
 C5 = 1000pF, 3KV CAPACITOR

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